

IN THE ABSTRACT

Please add the following abstract from the International Application following page 24.

In an electronic component mounting process for mounting electronic components (6) to a substrate, each of the electronic components having an adhesive layer on a surface to be bonded to the substrate is picked up with suction nozzle provided with individual heater, and a time taken for the mounting operation is so allotted that a first heating time of a duration from a moment when the suction nozzle comes into contact with the electronic component for picking it up till another moment immediately before it begins a mounting motion to the substrate is longer than a second heating time of a duration from the moment when the suction nozzle begins the mounting motion till another moment when it leaves the electronic component mounted to the substrate.